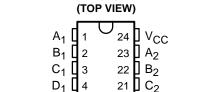
SCCS025B - MAY 1993 - REVISED OCTOBER 2001

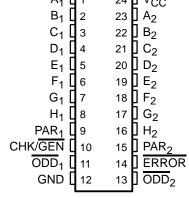
- **Function, Pinout, and Drive Compatible** With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- **Edge-Rate Control Circuitry for** Significantly Improved Noise Characteristics
- Ioff Supports Partial-Power-Down Mode Operation
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- Two 8-Bit Parity Generators/Checkers
- **Open-Drain Active-Low Parity-Error Output**
- **Expandable for Larger Word Widths**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- CY54FCT480T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT480T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

description

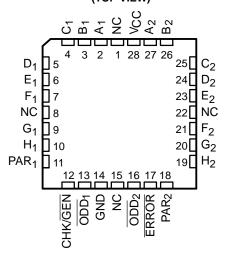
The 'FCT480T devices are high-speed, dual, 8-bit parity generators/checkers. Each parity generator/checker accepts eight data bits and one parity bit as inputs, and generates a sum and parity-error (ERROR) output. These devices can be used in odd-parity systems. ERROR is an open-drain output designed for easy expansion of



CY74FCT480T . . . P, Q, OR SO PACKAGE



CY54FCT480T...L PACKAGE (TOP VIEW)



NC - No internal connection

the word width by a wired-OR connection of several 'FCT480T devices. Because no additional logic is needed, the parity-generation or parity-checking times remain the same as for an individual 'FCT480T device.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

TA	PAC	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE Marking
	DIP – P	Tube	6.1	CY74FCT480BTPC	CY74FCT480BTPC
	QSOP - Q	Tape and reel	6.1	CY74FCT480BTQCT	FCT480B
-40°C to 85°C	SOIC - SO	Tube	6.1	CY74FCT480BTSOC	FCT480B
-40 C to 65 C		Tape and reel	6.1	CY74FCT480BTSOCT	FC1400B
	DIP – P	Tube	7.5	CY74FCT480ATPC	CY74FCT480ATPC
	QSOP - Q	Tape and reel	7.5	CY74FCT480ATQCT	FCT480A
–55°C to 125°C	LCC – L	Tube 7		CY54FCT480BTLMB	

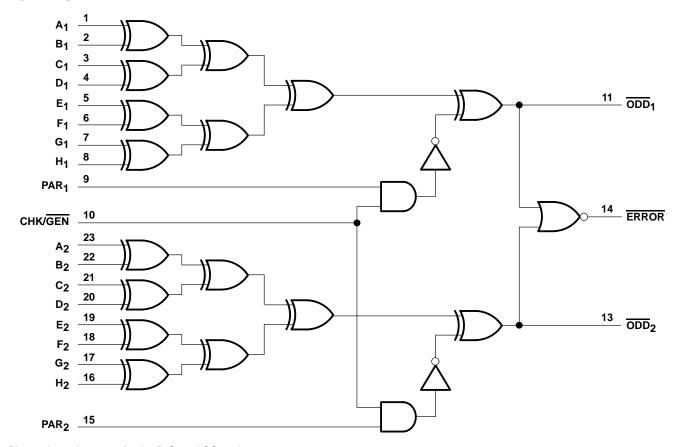
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUT	S				OUTPUTS			
A ₁ -H ₁	A ₂ -H ₂	CHK/GEN	PAR ₁	PAR ₂	ODD ₁	ODD ₂	ERROR		
		Н	Н	Н	L	L	Н		
	Number of	Н	L	Н	Н	L	L		
	A ₂ -H ₂ inputs,	н	Н	L	L	Н	L		
	high is even	н	L	L	Н	Н	L		
Number of		L	X	Χ	Н	Н	L		
A ₁ -H ₁ inputs, high is even		Н	Н	Н	L	Н	L		
	Number of	н	L	Н	Н	Н	L		
	inputs A ₂ –H ₂ , high is odd	н	Н	L	L	L	Н		
		н	L	L	Н	L	L		
		L	X	Χ	Н	L	L		
		Н	Н	Н	Н	L	L		
	Number of	н	L	Н	L	L	Н		
	A ₂ –H ₂ inputs,	Н	Н	L	Н	Н	L		
	high is even	н	L	L	L	Н	L		
Number of		L	X	Χ	L	Н	L		
A ₁ -H ₁ inputs, high is odd		Н	Н	Н	Н	Н	L		
	Number of	н	L	Н	L	Н	L		
	A ₂ -H ₂ inputs,	Н	Н	L	Н	L	L		
	high is odd	н	L	L	L	L	Н		
		L	Χ	Χ	L	L	Н		

H = High logic level, L = Low logic level, X = Don't care

logic diagram



Pin numbers shown are for the P, Q, and SO packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	
DC output voltage range	
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): P package	67°C/W
(see Note 2): Q package	
(see Note 2): SO package	46°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



CY54FCT480T, CY74FCT480T DUAL 8-BIT PARITY GENERATORS/CHECKERS

SCCS025B - MAY 1993 - REVISED OCTOBER 2001

recommended operating conditions (see Note 3)

		CY54FCT480T		0T	CY	0T	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
ІОН	High-level output current			-12			-32	mA
l _{OL}	Low-level output current			32			64	mA
T _A	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEGT GOLUDITIONS	CY	54FCT48	0Т	CY	74FCT48	80T	LINUT				
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT				
Maria	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$		-0.7	-1.2				V				
VIK	V _{CC} = 4.75 V, I _{IN} = -18 mA					-0.7	-1.2	V				
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$	2.4	3.3									
Voн	V _{CC} = 4.75 V				2.4	3.3		V				
	$I_{OH} = -32 \text{ mA}$				2							
Voi	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$		0.3	0.55				V				
VOL	$V_{CC} = 4.75 \text{ V}, \qquad I_{OL} = 64 \text{ mA}$					0.3	0.55	V				
V_{hys}	All inputs		0.2			0.2		V				
11	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$			5				μA				
'1	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = V_{CC}$						5					
lΗ	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			±1				μА				
	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						±1	μΛ				
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$	±1					μΑ					
IΙL	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						±1	μΛ				
I _{off}	$V_{CC} = 0 \text{ V}, \qquad V_{OUT} = 4.5 \text{ V}$			±1			±1	μΑ				
los‡	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$	-60	-120	-225				mA				
1051	V _{CC} = 5.25 V, V _{OUT} = 0 V				-60	-120	-225	ША				
lozh	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 2.7 \text{ V}$			10				μA				
'OZH	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 2.7 \text{ V}$						10	μΑ				
lozi	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0.5 \text{ V}$			-10				μA				
lozL	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0.5 \text{ V}$						-10	μΑ				
loo	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA				
Icc	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2] ""A				
Aloo	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}$, $f_1 = 0$, Outputs open		0.5	2				mA				
∆ICC	V _{CC} = 5.25 V, V _{IN} = 3.4 V\$, f ₁ = 0, Outputs open					0.5	2	IIIA				

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

[§] Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND

SCCS025B - MAY 1993 - REVISED OCTOBER 2001

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		TEST CONDITION	ue.	CY	54FCT48	0T	CY	74FCT48	0T	LINUT
PARAMETER		TEST CONDITION	V 5	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
ICCD¶	$V_{CC} = 5.5 \text{ V}$, Outp One bit switching a $V_{IN} \le 0.2 \text{ V}$ or V_{IN}		0.06	0.12				mA/		
ICCD"	V_{CC} = 5.25 V, Out One bit switching a $V_{IN} \le 0.2$ V or V_{IN}					0.06	0.12	MHz		
		One bit switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	$V_{CC} = 5.5 \text{ V},$ $f_0 = 0 \text{ MHz},$ Outputs open	at 50% duty cycle	V _{IN} = 3.4 V or GND		1	2.4				
			$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		2.5	5				
IC#			V _{IN} = 3.4 V or GND		6.5	21				mA
10"		One bit switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	V _{CC} = 5.25 V,	at 50% duty cycle	V _{IN} = 3.4 V or GND					1	2.4	
	Outputs open	f ₀ = 0 MHz, Outputs open 16 bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					2.5	5	
		at 50% duty cycle	V _{IN} = 3.4 V or GND					6.5	21	
Ci					5	10		5	10	pF
Co					9	12		9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Where:

I_C= Total supply current

ICC= Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

DH= Duty cycle for TTL inputs high

N_T= Number of TTL inputs at D_H

I_{CCD}= Dynamic current caused by an input transition pair (HLH or LHL)

f₀= Clock frequency for registered devices, otherwise zero

f₁= Input signal frequency

 N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



This parameter is derived for use in total power-supply calculations.

 $^{^{\#}}$ IC=ICC + \triangle ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

CY54FCT480T, CY74FCT480T DUAL 8-BIT PARITY GENERATORS/CHECKERS

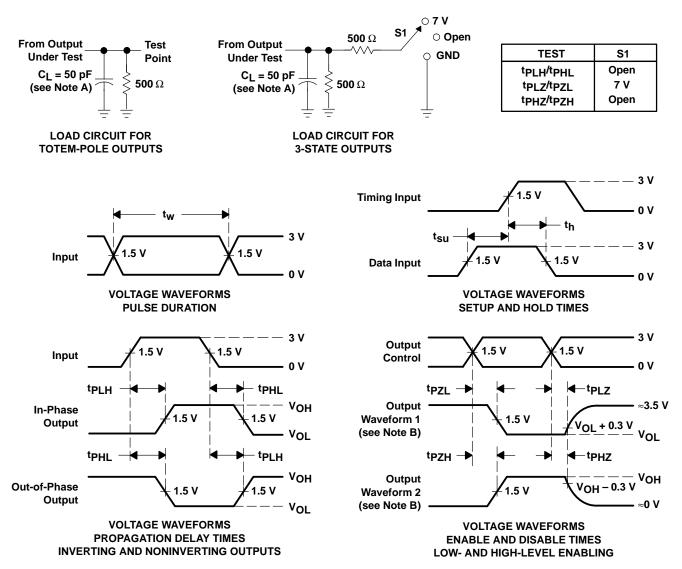
SCCS025B - MAY 1993 - REVISED OCTOBER 2001

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT480AT	CY54FCT480BT	CY74FCT480BT	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN MAX	MIN MAX	MIN MAX	UNIT	
t _{PLH}	А	ODD	7.5	7	6.1	ns	
t _{PHL}	^	(see Figure 1)	7	6.6	6.1	115	
t _{PLH}	CHK/ GEN	ODD	6.5	6.3	5.9	ns	
^t PHL	CHROLIN	(see Figure 1)	7.5	7.4	5.9	115	
t _{PLH} †	А	ERROR	7	7	6.1	no	
tpHL	A	(see Figure 2)	8.5	8.1	6.5	ns	
^t PLH	CHK/ GEN	ERROR	7.5	7.1	5.7	ns	
^t PHL	CHN/GEN	(see Figure 2)	7	6.9	5.5	115	

 $^{^{\}dagger}$ tpLH is measured up to VOUT = VOL + 0.3 V.

PARAMETER MEASUREMENT INFORMATION



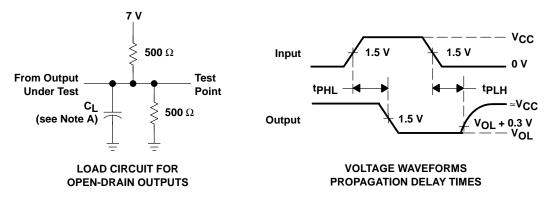
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCCS025B - MAY 1993 - REVISED OCTOBER 2001

PARAMETER MEASUREMENT INFORMATION FOR OPEN-DRAIN OUTPUTS



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns. $t_f \leq 3$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CY54FCT480BTLMB	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
CY74FCT480ATPC	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480ATPCE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480BTPC	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480BTPCE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480BTQCT	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $^{(1)}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



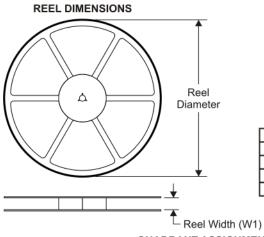
PACKAGE OPTION ADDENDUM

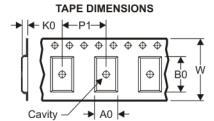
www.ti.com 11-Nov-2009

PACKAGE MATERIALS INFORMATION

www.ti.com 29-Jul-2009

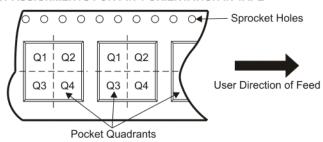
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT480BTQCT	SSOP/ QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

www.ti.com 29-Jul-2009



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT480BTQCT	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications Products Amplifiers amplifier.ti.com Audio www.ti.com/audio Data Converters Automotive dataconverter.ti.com www.ti.com/automotive **DLP® Products** Broadband www.dlp.com www.ti.com/broadband DSP Digital Control dsp.ti.com www.ti.com/digitalcontrol Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Interface Military www.ti.com/military interface.ti.com Optical Networking Logic logic.ti.com www.ti.com/opticalnetwork Power Mgmt power.ti.com Security www.ti.com/security Telephony Microcontrollers microcontroller.ti.com www.ti.com/telephony www.ti-rfid.com Video & Imaging www.ti.com/video RF/IF and ZigBee® Solutions www.ti.com/lprf Wireless www.ti.com/wireless

> Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated